

U.S. Patent Appln. Ser. No. 10/807,417 entitled "Microcap Wafer Bonding Apparatus" to Fazzio; Avago Technologies Attorney Docket No. 10030899-1; Woods Patent Law Docket No. P AVG 188.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: R. Shane Fazzio

Examiner Name: Monica Lewis

Serial No.: 10/807,417

Group Art Unit: 2822

Filed: March 23, 2004

Attorney Docket No.: 10030899-1

Confirmation No.: 3854

Title: Microcap Wafer Bonding Apparatus

**REQUEST FOR CONTINUING EXAMINATION AND
PRELIMINARY AMENDMENT AND RESPONSE**

Commissioner for Patents
P.O. Box 1450
Arlington, VA 22313-1450

Sir:

In response to the Final Office Action dated August 29, 2007, and in conjunction with the Request for Continuing Examination submitted herewith, Applicants respectfully request entry of the preliminary amendments set forth herein, and allowance of the above-identified patent application as amended herein:

DATE OF DEPOSIT: August 27, 2007

CERTIFICATE OF ELECTRONIC DEPOSIT: I hereby certify that all paper(s) described herein are being filed electronically with the United States Patent and Trademark Office on the date indicated above and addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Signature: Thomas F. Woods

Printed Name: Thomas F. Woods, Reg. No. 36,726.